

! Deadline: Please note that the deadline for the booth reservation is **May 25th, 2019.**

Registration Form for the EMLC 2019 Technical Exhibition

Please fax or e-mail your registration form to **Dr. Uwe Behringer**

Fax: ++49-7073-50216

E-mail: uwe.behringer.ubc@t-online.de

Booth size and equipment:

For a booth size **A** (2 x 2 meters): one table, two chairs are included.

- Please reserve one booth size **A**

For a booth size **B** (2 x 3 meters): one table, two chairs are included.

- Please reserve one booth size **B**

For a booth size **C** (2 x 4 meters): two tables, two chairs are included.

- Please reserve one booth size **C**

Pin Boardy are available on request.

Please identify if you need a Pin Board. The fee for a pin board is € 80,- for the 2 days.

Pin Board size (130 cm x 160 cm; W x H)

- Electrical power (**220 Volt, German plug !!**)
- We do not require any pinboard, we will provide our own booth equipment**

Company / contact person: Please provide your contact information: (phone; e-mail; mailing address)

Organizers

VDE/VDI-Society Microelectronics,
Microsystems- and Precision Engineering (GMM)

Dr.-Ing. Ronald Schnabel

Stresemannallee 15 Phone: +49-69-6308 227
60596 Frankfurt/Main Fax: +49-69-6308 9828
Germany E-Mail: gmm@vde.com

In cooperation with:

UBC Microelectronics

Dr. Uwe Behringer
EMLC 2018 Conference Chair

Auf den Beeten 5, Phone: +49-171-4553196
D-72119 Ammerbuch Fax: +49-7073-50216
Germany E-Mail: uwe.behringer.ubc@t-online.de

Venue



Hilton Hotel in Dresden



Dresden at the river Elbe

The EMLC 2019 International Program Committee

Conference Chairs *Behringer, Uwe*, UBC Microelectronics, Ammerbuch, Germany
Finders Jo, ASML, Veldhoven, The Netherlands

Conference Co-Chairs *Cannolly, Brid*, Toppan Photomasks, Dresden, Germany
Gale, Chris, Applied Materials, Dresden, Germany
Hayashi, Naoya, DNP, Saitama, Japan

Program Chairs *Stolberg, Ines*, Vistec Electron Beam, Jena, Germany
Erdmann, Andreas, Fraunhofer IISB, Erlangen, Germany

Program Co-Chairs *Seltmann, Rolf*, Globalfoundries, Dresden, Germany
Sarlette, Daniel, Infineon, Dresden, Germany

Other Members :

Ehrmann, Albrecht, Carl Zeiss SMT GmbH, Oberkochen, Germany
Farrar, Dave, Hoya Corporation, London, UK
Galler, Reinhard, Equicon, Jena, Germany
Jonckheere, Rik, IMEC vzw, Leuven, Belgium
Kapilevich, Izak, AMAT, USA
Le Gratiot, Bertrand, STMicroelectronics, Crolles, France
Loeschner, Hans, IMS Nanofabrication GmbH, Vienna, Austria
Muehlberger, Michael, Profactor GmbH, Steyr-Gleink, Austria
Pain, Laurent, CEA-LETI, Grenoble, France
Peters, Jan Hendrik, bmbg consult, Radebeul, Germany
Roeth, Klaus-Dieter, KLA-Tencor MIE, Weilburg, Germany
Savari, Serap, Texas A&M University College Station, USA
Scheruebl, Thomas, Carl Zeiss SMT GmbH, Jena, Germany
Schnabel, Ronald, VDE/VDI-GMM, Frankfurt am Main, Germany
Schulze, Steffen, Mentor Graphics Corp., Wilsonville, OR, USA
Tschinkl, Martin, AMTC, Dresden, Germany
Waelpoel, Jacques, ASML, Veldhoven, The Netherlands
Wiley, Jim, ASML US Inc., Santa Clara, CA, USA
Wolf, Hermann, Photonics MZD GmbH, Dresden, Germany
Wurm, Stefan, ATICE LLC, Albany, NY, USA
Yoshitake, Shusuke, NuFlare, Japan
Zurbrick, Larry, Keysight Technologies, Santa Clara, CA, USA

Cover picture:
Courtesy of Toppan Photomasks

Call for Papers



The 35th European
Mask and Lithography
Conference

EMLC 2019

June 17 – 19, 2019
Hilton Hotel Dresden, Germany

www.emlc-conference.com



The VDE/VDI-Society Microelectronics, Microsystems and Precision Engineering (GMM) and UBC Microelectronics in cooperation with BACUS, PMJ, SEMI-Europe, and SPIE, are pleased to announce the

35th European Mask and Lithography Conference, EMLC 2019 at the Hilton Hotel in Dresden, Germany June 17 - June 19, 2019

The focus of this 3 day conference is state-of-the-art of mask technology and lithography, such as mask manufacturing, mask business, lithography and mask applications, emerging mask & lithography technologies, and mask & lithography equipment.

This conference has annually brought together scientists, researchers, engineers and developers from around the world to present papers at the forefront of research, manufacturing and application. It provides a place where both specialists from industry and advanced research as well as equipment and software providers become acquainted with new developments and results.

Conference Schedule

The conference will be opened on Monday June 17th 2019 with a Tutorial from 2:00 PM to 05:00 PM. The Get Together and a Poster Session will start at 7:00 PM.

On Tuesday, June 18th, the conference will start at 9:00 AM and close on Wednesday, June 19th, 2019, at 6:30 PM.

Conference dinner is scheduled on Tuesday evening.

Technical Exhibition

On Tuesday and Wednesday (June 18th and 19th 2019) there will be a technical exhibition with booth space for about 20 exhibitors. Presentation tables and pin boards will be available. To be part of this Technical Exhibition, please return the enclosed registration form to the Conference Exhibition Organization as soon as possible, since exhibition space is limited.

Exhibition Organization

Dr. Uwe Behringer,
UBC Microelectronics,
Auf den Beeten 5
D-72119 Ammerbuch
Germany
Phone: +49-171-4553196
Fax: +49-7073-50216
E-Mail: uwe.behringer.ubc@t-online.de

Abstract Information

Abstract quality will be the basis for selection of conference presentations. The abstracts will be assessed for:

- Originality of work
- Specific results reported
- Potential impact and interest to the attendees.

Therefore, we highly recommend that your abstract contains enough detail to clearly describe the content of your presentation. We recommend an abstract length of **two pages** (including figures, diagrams, formatted text) as Word and PDF.

Commercial papers, papers with no new research / development content, and papers where significant information is missing will not be accepted.

All accepted Abstracts will be made available at the EMLC 2019 website.

In order to submit your abstract to SPIE, please open the website www.emlc-conference.com

▪ **Deadline for Abstracts: Friday, April 12th, 2019**

By submitting an abstract you agree to:

- present your work in person at the conference
- and to submit a manuscript and/or your presentation materials in time.

Authors will be notified of the acceptance of their submissions **by Friday, May 3rd, 2019**; further manuscript format and layout instructions will be provided at that time.

Please note that we plan to have oral and poster presentations.

Deadline for submission your manuscripts to SPIE: June 18th, 2019.

All manuscripts will be subjected to a critical peer review before they are accepted for publication.

Please note that late submissions may not be published.

Manuscripts for the EMLC 2019 Proceedings will be published by SPIE and made available at the SPIE Digital Library.

PDF files of presentation materials (oral, poster), submitted until July 20th, 2019, will be published at the emlc-conference.com website, protected by a pin code.

For further information concerning the submission procedure, please visit our homepage www.emlc-conference.com

Conference Topics

Mask Manufacturing and Mask Business

- Multi-Beam Writing of Leading-Edge Masks and NIL Master Templates
- Mask Data Preparation
- Pattern Generation: Writing, Etch, etc.
- Photomask Processes & Materials
- Metrology Tools & Technologies
- Defect Inspection & Repair
- Cleaning & Haze
- Pellicles & Mask Boxes
- Mask Process Yield & Cycle Time
- Photomasks for RET (OPC, ILT) ; PSM
- Mask Business and Management
- Mask Cost and Mask Development Strategy
- Future Mask Demand

Lithographic Systems and Processes

- Optical Resolution Enhancements including OPC, Free-form Illumination, Source-Mask-optimization (SMO) and Inverse Lithography Technology (ILT)
- Material-and Process driven Resolution Enhancements including Multiple Patterning and Chemical Shrinking
- Immersion Lithography including Defectivity
- Lithography Process Control
- Lithography and Etch Simulation including rigorous physical/chemical Models and Compact Models

Emerging Mask and Lithography Technologies

- EUV-Lithography including Masks, Materials Processes and Infrastructure.
- Nano-Imprint Lithography (NIL)
- Directed Self-Assembly (DSA) including High Chi Materials, Defectivity Control, and new Processes
- Direct Write / Maskless Technologies

Emerging Applications

- Non-IC Applications including Si-Photonics, Flat Panel Displays and MEMS
- Lithographic Systems for non-IC Applications, including
- Laser Direct Write, Interference Lithography, and Mask Aligners

EMLC 2019 Technical Exhibition

in conjunction with the

35th European Mask and Lithography Conference EMLC 2019

June 17th – June 19th, 2019
Hilton Hotel, Dresden, Germany
<http://www.emlc-conference.com>

The 2 days **Technical Exhibition** will take place on Tuesday; June 18th and Wednesday, June 19th, 2019 during the conference days. Presentation tables and pin boards will be available. There is booth space for about 20 exhibitors and space will be allocated according to the time when application are received.

There are three different both sizes and prices available.:

<u>Booth size</u>	<u>Fee</u>
A (2 x 2 meters)	€ 1.190
B (2 x 3 meters)	€ 1.440
C (2 x 4 meters)	€ 1.690

VAT of 19% is NOT included in booth pricing

Payments can be made by bank draft only (no credit card payments will be accepted). Please make sure that the payment includes the bank transfer fee.

Please make payment to: UBC Microelectronics
Project #: TE 2019

Bank : Kreissparkasse Tuebingen, Germany
Account #: 4041649
Bank code: (BLZ 641 500 20)
SWIFT-BIC: SOLADES1TUB
IBAN: DE70 6415 0020 0004 041649
VAT ID#: DE 163 546 811

Please be aware: If you are not a conference attendee but an exhibitor only the VDE will charge you € 150,- per person. This fee includes coffee- and lunch breaks. The conference dinner is also included.

**For more information please contact:
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